TABLE OF CONTENTS

Features 1
Enhanced Product Features1
Applications1
Typical Application Circuits1
General Description1
Revision History
Specifications
Absolute Maximum Ratings5
REVISION HISTORY
6/12—Rev. 0 to Rev. A
Changes to Ordering Guide12
2/11—Revision 0: Initial Version

Thermal Resistance	5
ESD Caution	5
Pin Configurations and Function Descriptions	6
Typical Performance Characteristics	7
Applications Information	10
Thermal Considerations	10
Outline Dimensions	12
Ordering Guide	12

SPECIFICATIONS

 $V_{\rm IN}$ = 12 V, $I_{\rm OUT}$ = 100 $\mu A,$ $C_{\rm IN}$ = $C_{\rm OUT}$ = 1 $\mu F,$ $T_{\rm A}$ = 25°C, unless otherwise noted.

Table 1.

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
INPUT VOLTAGE RANGE	V _{IN}	$T_{J} = -55^{\circ}C \text{ to } +125^{\circ}C$	4		28	V
OPERATING SUPPLY CURRENT	I _{GND}	$I_{OUT} = 0 \ \mu A$ $I_{OUT} = 0 \ \mu A, V_{IN} = V_{OUT} + 0.5 \ V \ or \ 4 \ V \ (whichever is greater), T_J = -55^{\circ}C \ to +125^{\circ}C$		28	80	μΑ μΑ
		$I_{OUT} = 100 \ \mu A$ $I_{OUT} = 100 \ \mu A, V_{IN} = V_{OUT} + 0.5 \ V \text{ or } 4 \ V \text{ (whichever is}$		35	120	μΑ μΑ
		greater), $T_J = -55^{\circ}C$ to $+125^{\circ}C$		74		•
		$I_{OUT} = 1 \text{ mA}$ $I_{OUT} = 1 \text{ mA}, V_{IN} = V_{OUT} + 0.5 \text{ V or } 4 \text{ V} \text{ (whichever is greater)}, T_1 = -55^{\circ}\text{C} \text{ to } +125^{\circ}\text{C}$		74	340	μΑ μΑ
		$I_{OUT} = 10 \text{ mA}$		300		μA
		$I_{OUT} = 10 \text{ mA}, V_{IN} = V_{OUT} + 0.5 \text{ V or } 4 \text{ V} \text{ (whichever is greater)}, T_J = -55^{\circ}\text{C} \text{ to } +125^{\circ}\text{C}$			900	μA
		100 μ A < I _{OUT} < 50 mA, V _{IN} = V _{OUT} + 0.5 V or 4 V (whichever is greater), T _J = -55°C to +125°C		1185	2115	μA
SHUTDOWN CURRENT	I _{GND-SD}	EN = GND $EN = GND, T_{J} = -55^{\circ}C \text{ to } +125^{\circ}C$		0.7	1.7	μΑ μΑ
OUTPUT						
Fixed Output	V _{out}	$I_{OUT} = 100 \mu\text{A}$	-0.5		+0.5	%
Voltage Accuracy		$100 \mu A < I_{OUT} < 50 m A$ $100 \mu A < L_{OUT} < 50 m A T = .55°C to +125°C$	-1 -2		+1 +2	% %
Adjustable Output ¹	V _{OUT}	$100 \ \mu A < I_{OUT} < 50 \ mA, T_J = -55^{\circ}C \ to +125^{\circ}C$ $I_{OUT} = 100 \ \mu A$	-2	1.2250	+2	% V
Voltage Accuracy	VOUT	$100 \mu\text{A} < I_{OUT} < 50 \text{mA}$	1.2100	1.2250	1.2371	V
Voltage / lecalacy		$100 \ \mu\text{A} < I_{\text{OUT}} < 50 \ \text{mA}, T_1 = -55^{\circ}\text{C} \text{ to } +125^{\circ}\text{C}$	1.2005		1.2495	v
Noise (10 Hz to 100 kHz)		$V_{OUT} = 1.6 V, C_{OUT} = 1 \mu F$		146		μV rm:
, , , , , ,	NOISE	$V_{OUT} = 1.6 \text{ V}, \text{ C}_{OUT} = 10 \mu\text{F}$		124		μV rms
		$V_{OUT} = 5 V, C_{OUT} = 1 \mu F$		340		μV rms
		$V_{OUT} = 5 V, C_{OUT} = 10 \mu F$		266		μV rms
REGULATION						
Line Regulation	$\Delta V_{OUT} / \Delta V_{IN}$	$V_{IN} = (V_{OUT} + 0.5 V)$ to 28 V, $T_J = -55^{\circ}C$ to $+125^{\circ}C$	-0.02		+0.02	%/V
Load Regulation ²	$\Delta V_{OUT} / \Delta I_{OUT}$	1 mA < I _{out} < 50 mA		0.001		%/mA
		$1 \text{ mA} < I_{OUT} < 50 \text{ mA}, T_J = -55^{\circ}\text{C} \text{ to } +125^{\circ}\text{C}$			0.005	%/mA
DROPOUT VOLTAGE ³	V _{DROPOUT}	I _{OUT} = 10 mA		55		mV
		$I_{OUT} = 10 \text{ mA}, T_J = -55^{\circ}\text{C} \text{ to} + 125^{\circ}\text{C}$			105	mV
		$I_{OUT} = 50 \text{ mA}$		275		mV
		$I_{OUT} = 50 \text{ mA}, T_J = -55^{\circ}\text{C to} + 125^{\circ}\text{C}$			480	mV
START-UP TIME ⁴	t _{start-up}			200		μs
CURRENT LIMIT THRESHOLD ⁵	I _{LIMIT}		55	90	140	mA
THERMAL CHARACTERISTICS						
Thermal Shutdown Threshold	TS _{SD}	T, rising		150		°C
Thermal Shutdown Hysteresis	TS _{SD-HYS}			15		°C
EN CHARACTERISTICS						
EN Input						
Logic High	V _{IH}	$4 \text{ V} \le \text{V}_{\text{IN}} \le 28 \text{ V}$	1.8			V
Logic Low	V _{IL}	$4 \text{ V} \le \text{V}_{\text{IN}} \le 28 \text{ V}$			0.4	V
Leakage Current	V _{I-LEAKAGE}	EN = GND EN = IN		0.1 0.5	1 1	μΑ μΑ
ADJ INPUT BIAS CURRENT (ADP1720-EP ADJUSTABLE)	ADJ _{I-BIAS}			30	100	nA

ADP1720-EP

Parameter	Symbol	Conditions	Min Typ	Мах	Unit
POWER SUPPLY REJECTION RATIO	PSRR	$f = 120 \text{ Hz}, V_{IN} = 8 \text{ V}, V_{OUT} = 1.6 \text{ V}$	-90		dB
		$f = 1 \text{ kHz}, V_{IN} = 8 \text{ V}, V_{OUT} = 1.6 \text{ V}$	-80		dB
		$f = 10 \text{ kHz}, V_{IN} = 8 \text{ V}, V_{OUT} = 1.6 \text{ V}$	-60		dB
		$f = 120 Hz, V_{IN} = 8 V, V_{OUT} = 5 V$	-83		dB
		$f = 1 \text{ kHz}, V_{IN} = 8 \text{ V}, V_{OUT} = 5 \text{ V}$	-70		dB
		$f = 10 \text{ kHz}, V_{IN} = 8 \text{ V}, V_{OUT} = 5 \text{ V}$	-50		dB

¹ Accuracy when OUT is connected directly to ADJ. When OUT voltage is set by external feedback resistors, absolute accuracy in adjust mode depends on the tolerances of resistors used.

² Based on an end-point calculation using 1 mA and 50 mA loads. See Figure 6 for typical load regulation performance for loads less than 1 mA.

³ Dropout voltage is defined as the input-to-output voltage differential when the input voltage is set to the nominal output voltage. This applies only for output voltages above 4 V.

⁴ Start-up time is defined as the time between the rising edge of EN to OUT being at 95% of its nominal value. ⁵ Current limit threshold is defined as the current at which the output voltage drops to 90% of the specified typical value. For example, the current limit for a 5.0 V output voltage is defined as the current that causes the output voltage to drop to 90% of 5.0 V, or 4.5 V.

ABSOLUTE MAXIMUM RATINGS

Table 2.

1 4010 20	
Parameter	Rating
IN to GND	–0.3 V to +30 V
OUT to GND	–0.3 V to IN or +6 V (whichever is less)
EN to GND	–0.3 V to +30 V
ADJ to GND	–0.3 V to +6 V
Storage Temperature Range	–65°C to +150°C
Operating Junction Temperature Range	–55°C to +125°C
Soldering Conditions	JEDEC J-STD-020

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

THERMAL RESISTANCE

 θ_{JA} is specified for the worst-case conditions, that is, a device soldered in a circuit board for surface-mount packages.

Table 3. Thermal Resistance

Package Type	θ _{JA}	θ _{JC}	Unit
8-Lead MSOP	246	66	°C/W

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATIONS AND FUNCTION DESCRIPTIONS

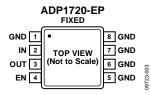




Figure 3. 8-Lead MSOP Pin Configuration—Fixed Output Voltage

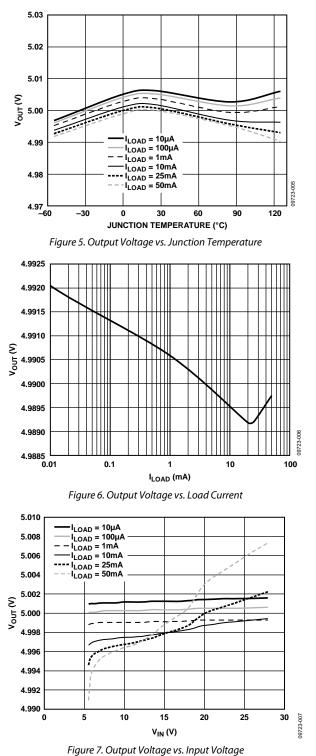
Figure 4. 8-Lead MSOP Pin Configuration—Adjustable Output Voltage

Table 4. Pin Function Descriptions

	Pin No.				
Fixed Adjustable Mnemonic		Mnemonic	Description		
1	N/A	GND	This pin is internally connected to ground.		
N/A	1	ADJ	Adjust. A resistor divider from OUT to ADJ sets the output voltage.		
2	2	IN	Regulator Input Supply. Bypass IN to GND with a 1 μ F or greater capacitor.		
3	3	OUT	Regulated Output Voltage. Bypass OUT to GND with a 1 μ F or greater capacitor.		
4	4	EN	Enable Input. Drive EN high to turn on the regulator; drive it low to turn off the regulator. For automatic startup, connect EN to IN.		
5	5	GND	Ground.		
6	6	GND	Ground.		
7	7	GND	Ground.		
8	8	GND	Ground.		

TYPICAL PERFORMANCE CHARACTERISTICS

 V_{IN} = 12 V, V_{OUT} = 5 V, I_{OUT} = 100 μ A, C_{IN} = C_{OUT} = 1 μ F, T_A = 25°C, unless otherwise noted.



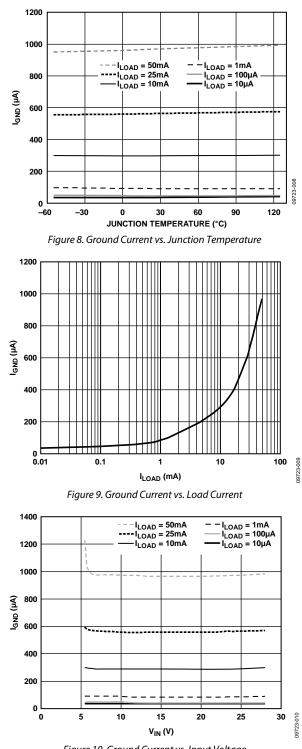
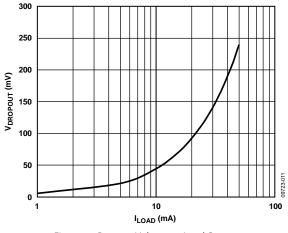
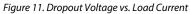


Figure 10. Ground Current vs. Input Voltage

ADP1720-EP





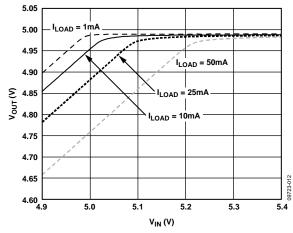


Figure 12. Output Voltage vs. Input Voltage (in Dropout)

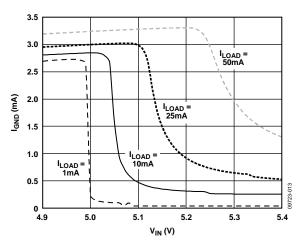


Figure 13. Ground Current vs. Input Voltage (in Dropout)

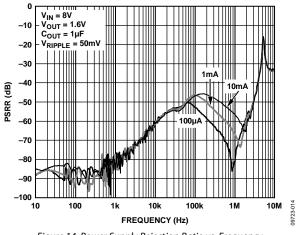


Figure 14. Power Supply Rejection Ratio vs. Frequency (1.6 V Adjustable Output)

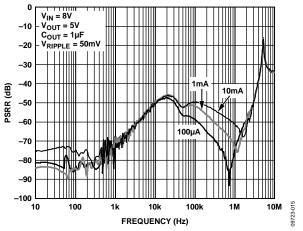


Figure 15. Power Supply Rejection Ratio vs. Frequency (5.0 V Fixed Output)

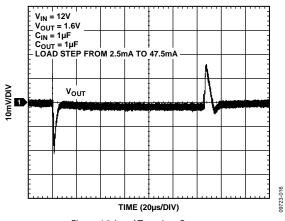


Figure 16. Load Transient Response

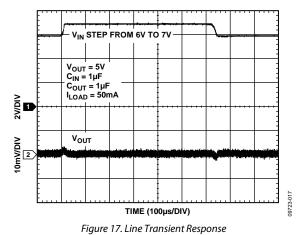
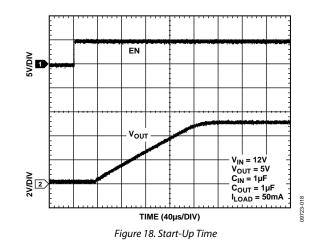


Figure 17. Line Transient Response



Data Sheet

APPLICATIONS INFORMATION THERMAL CONSIDERATIONS

To guarantee reliable operation, the junction temperature of the ADP1720-EP must not exceed 125°C. To ensure that the junction temperature stays below this maximum value, the user needs to be aware of the parameters that contribute to junction temperature changes. These parameters include ambient temperature, power dissipation in the power device, and thermal resistances between the junction and ambient air (θ_{JA}). The θ_{JA} number is dependent on the package assembly compounds used and the amount of copper to which the GND pins of the package are soldered on the PCB. Table 5 shows typical θ_{JA} values of the 8-lead MSOP package for various PCB copper sizes.

Copper Size (mm ²)	θ _{JA} (°C/W)
25	246
50	216
100	186
300	178
500	169

The junction temperature of the ADP1720-EP can be calculated from the following equation:

$$T_I = T_A + (P_D \times \theta_{IA}) \tag{3}$$

where:

 T_A is the ambient temperature.

 P_D is the power dissipation in the die, given by

$$P_D = [(V_{IN} - V_{OUT}) \times I_{LOAD}] + (V_{IN} \times I_{GND})$$
(4)

where:

 I_{LOAD} is the load current.

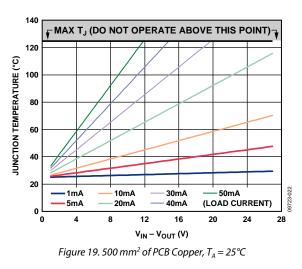
 I_{GND} is the ground current.

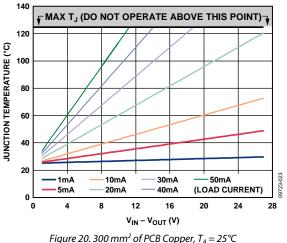
 V_{IN} and V_{OUT} are input and output voltages, respectively.

Power dissipation due to ground current is quite small and can be ignored. Therefore, the junction temperature equation simplifies to the following:

$$T_J = T_A + \{ [(V_{IN} - V_{OUT}) \times I_{LOAD}] \times \theta_{JA} \}$$
(5)

As shown in Equation 5, for a given ambient temperature, input-to-output voltage differential, and continuous load current, there exists a minimum copper size requirement for the PCB to ensure that the junction temperature does not rise above 125°C. Figure 19 to Figure 24 show junction temperature calculations for different ambient temperatures, load currents, V_{IN} to V_{OUT} differentials, and areas of PCB copper for the ADP1720-EP.





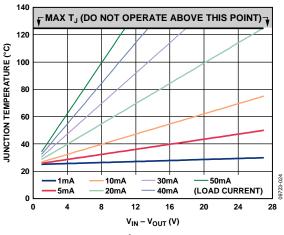
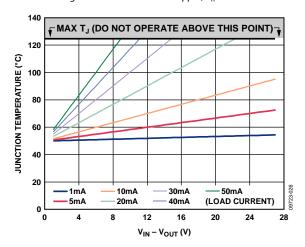


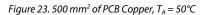
Figure 21. 100 mm² of PCB Copper, $T_A = 25^{\circ}C$

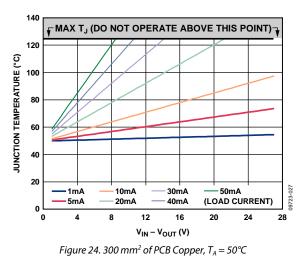
Data Sheet

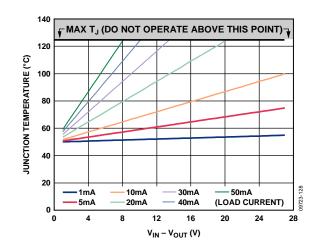
140 MAX TJ (DO NOT OPERATE ABOVE THIS POINT) 120 JUNCTION TEMPERATURE (°C) 100 80 60 40 20 50mA 10mA 30mA 1mA 97234 (LOAD CURRENT) 5mA 20mA 40mA 0 20 24 0 4 8 12 16 28 $V_{IN} - V_{OUT} (V)$

Figure 22. 25 mm² of PCB Copper, $T_A = 25^{\circ}C$









ADP1720-EP

Figure 25. 100 mm2 of PCB Copper, TA = 50°C

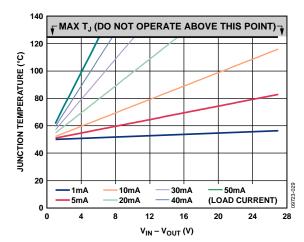
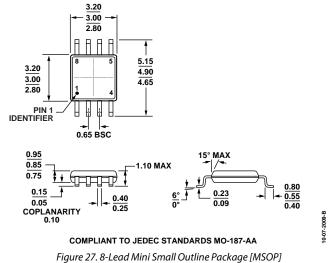


Figure 26. 25 mm2 of PCB Copper, $TA = 50^{\circ}C$

ADP1720-EP

OUTLINE DIMENSIONS



gure 27. 8-Lead Mini Small Outline Package [MS (RM-8) Dimensions shown in millimeters

ORDERING GUIDE

		Output			
Model ¹	Temperature Range	Voltage (V)	Package Description	Package Option	Branding
ADP1720TRMZ5-EP	–55°C to +125°C	5	8-Lead MSOP	RM-8	LKU
ADP1720TRMZ5-EP-R7	–55°C to +125°C	5	8-Lead MSOP	RM-8	LKU
ADP1720TRMZ3.3-EP	–55°C to +125°C	3.3	8-Lead MSOP	RM-8	LKT
ADP1720TRMZ3.3-EPR7	–55°C to +125°C	3.3	8-Lead MSOP	RM-8	LKT
ADP1720TRMZ-EP	–55°C to +125°C	1.225 to 5	8-Lead MSOP	RM-8	LG2
ADP1720TRMZ-EP-R7	–55°C to +125°C	1.225 to 5	8-Lead MSOP	RM-8	LG2

 1 Z = RoHS Compliant Part.

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